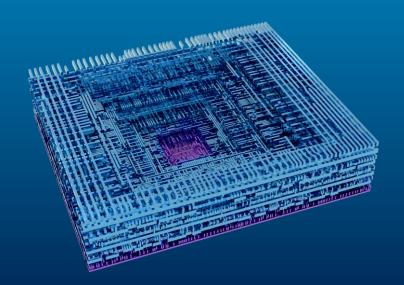


ASML plays a dual role in the AI era

The world's future will be AI and we are an integral part of it

ASML fuels the progress of AI chips with innovations in extreme performance requirements

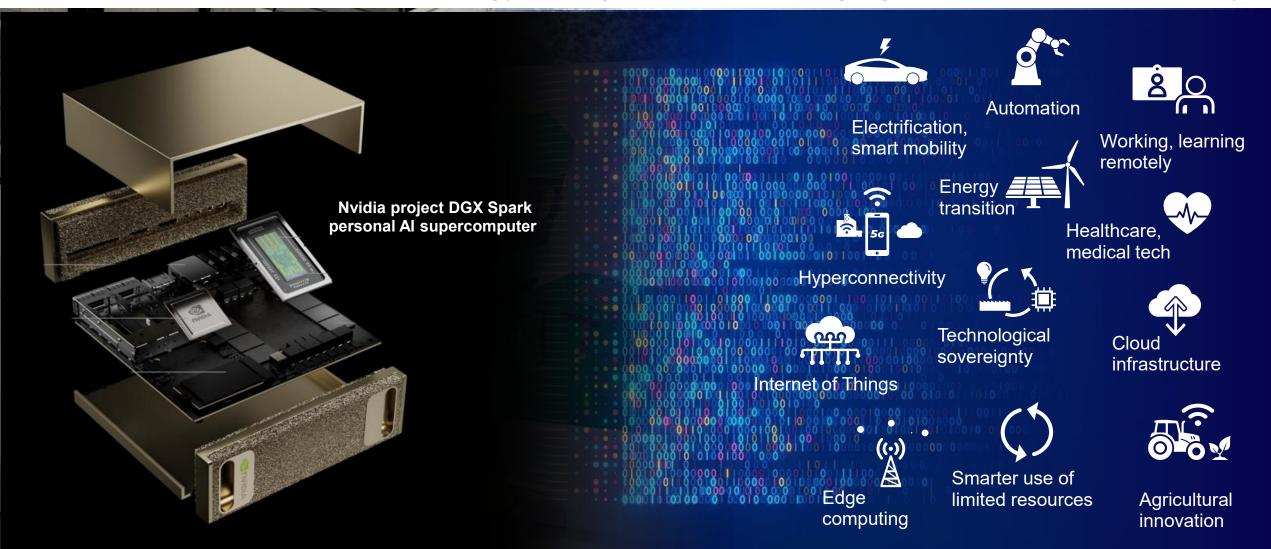


ASML incorporates AI to enhance scanner control and enable engineers to deal with large scale complexity



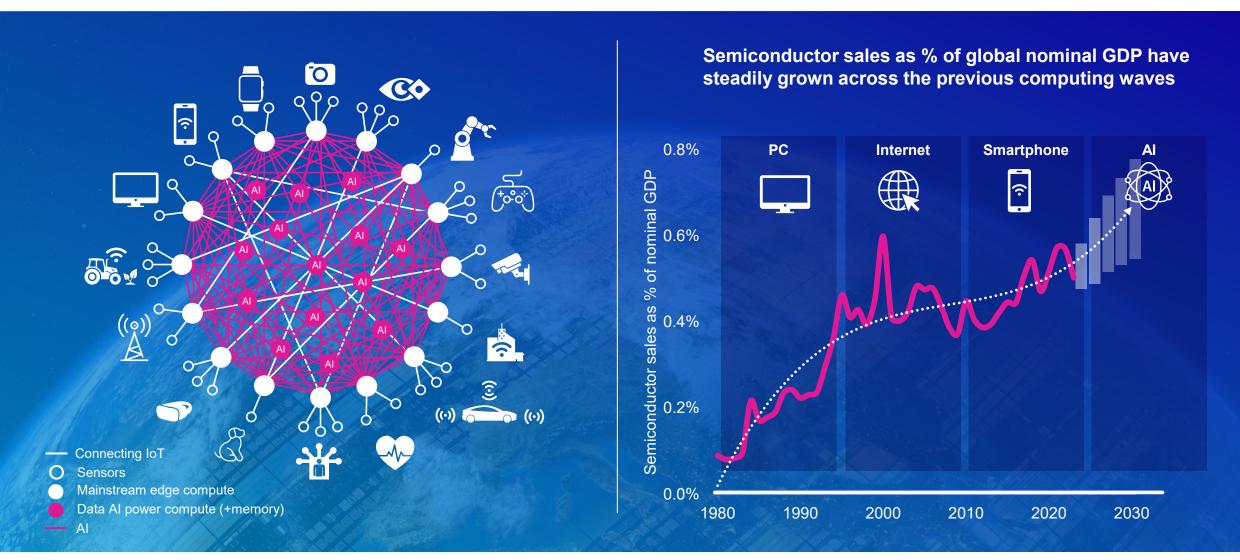
From chips everywhere to AI everywhere

It requires semiconductor strategy to align with the emerging needs of power/memory

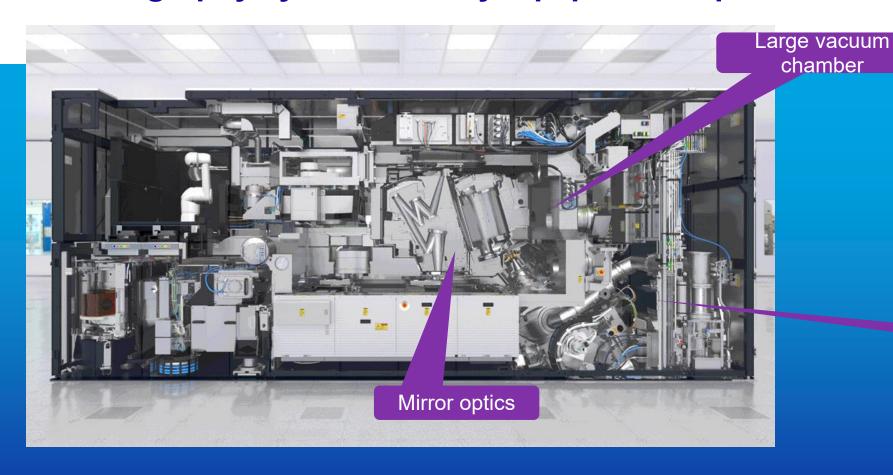


Al has strong potential to drive the entire semiconductor industry forward

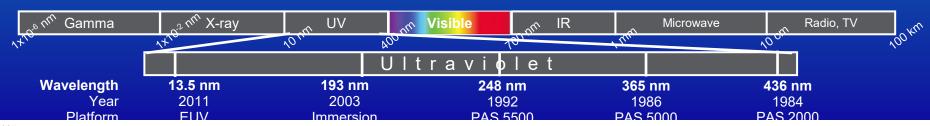
We will see AI penetrate all different segments of the semiconductor eco-system



ASML lithography system is a key equipment to produce Al chips



New light source



Lithography innovation keeps chip manufacturing affordable



80s

436 nm → 365 nm light $100 \text{ mm} \rightarrow 150 \text{ mm wafers}$

Moore's law number of transistors per chip doubles per 2 years, while the cost of computing is halved.



90s

248 nm → 193 nm light 150 mm \rightarrow 200 mm wafers 'step & repeat' → 'step & scan'



00s

200 mm \rightarrow 300 mm wafers Dry → immersion lithography Single stage → dual stage

10s/20s

Litho → Holistic litho Immersion → EUV EUV 0.33 → EUV 0.55



TWINSCAN XT:1400 Res: 65nm W: 300mm Wph: 145

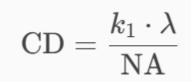


Wph: 190



High NA EUV Res: <8nm W: 300mm Wph: 185

Technology-wise, we had to move mountains



80s

10s/20s

Litho → Holistic litho Immersion → EUV EUV 0.33 → EUV 0.55

00s

200 mm → 300 mm wafers Dry → immersion lithography

Single stage → dual stage

90s

248 nm → 193 nm light 150 mm → 200 mm wafers 'step & repeat' → 'step & scan'

PAS 5500/60

Res: 450nm

W: 200mm

Wph: 48



Res: 65nm W: 300mm Wph: 145 TWINSCAN NXT:1950i Res: 38nm

Res: 38nm W: 300mm Wph: 190

System complexity

High NA EUV Res: <8nm

TWINSCAN NXE:3400B Res: 13nm

> W: 300mm Wph: 125

W: 300mm Wph: 185

PAS 2500/10

Res: 900nm

W: 150mm

436 nm \rightarrow 365 nm light

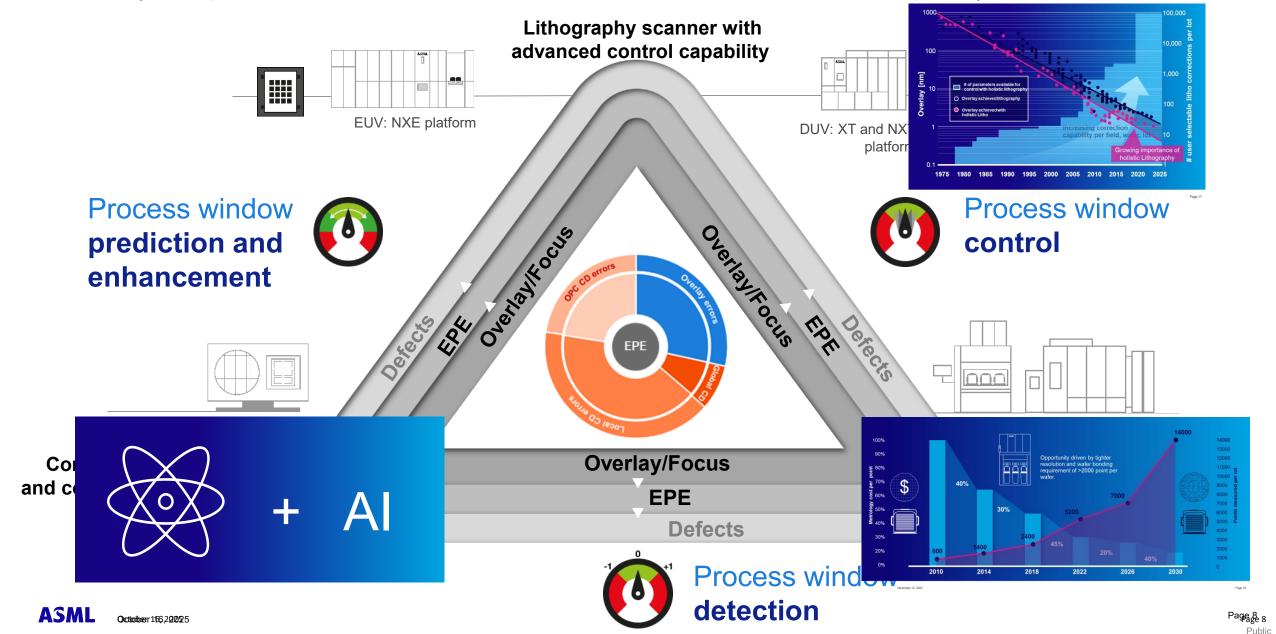
 $100 \text{ mm} \rightarrow 150 \text{ mm wafers}$

ASML

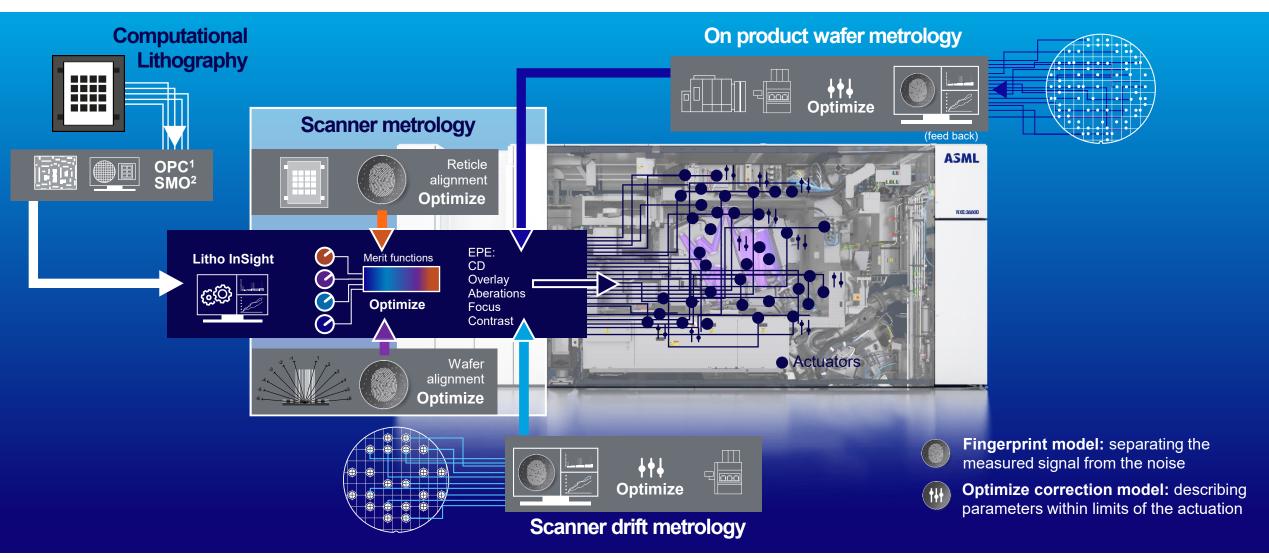
Wph: 66

Scanner control is inherently a holistic task and can benefit from Al

Driven by steep increase in number of actuators, amount of data, and complexity of models



Al applied to scanner control can help optimize most effectively the fastgrowing number of actuators, parameters, and mass metrology data





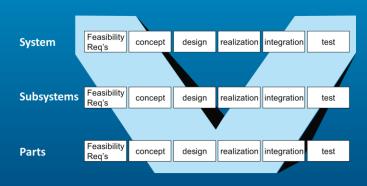
From design to manufacturing: multiple level large scale complexity

Modular system design integration of physics, hardware, software



7 product platforms

Concurrent engineering V-model



System integrator

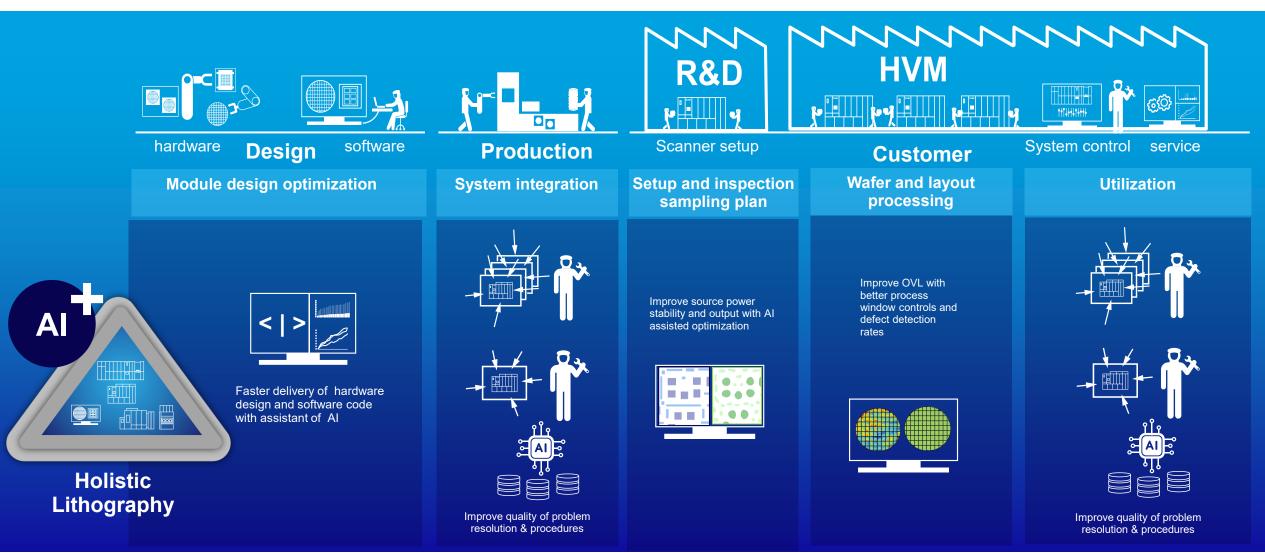


>250,000 unique parts

~90,000 work instructions ~15,000 D&E engineers

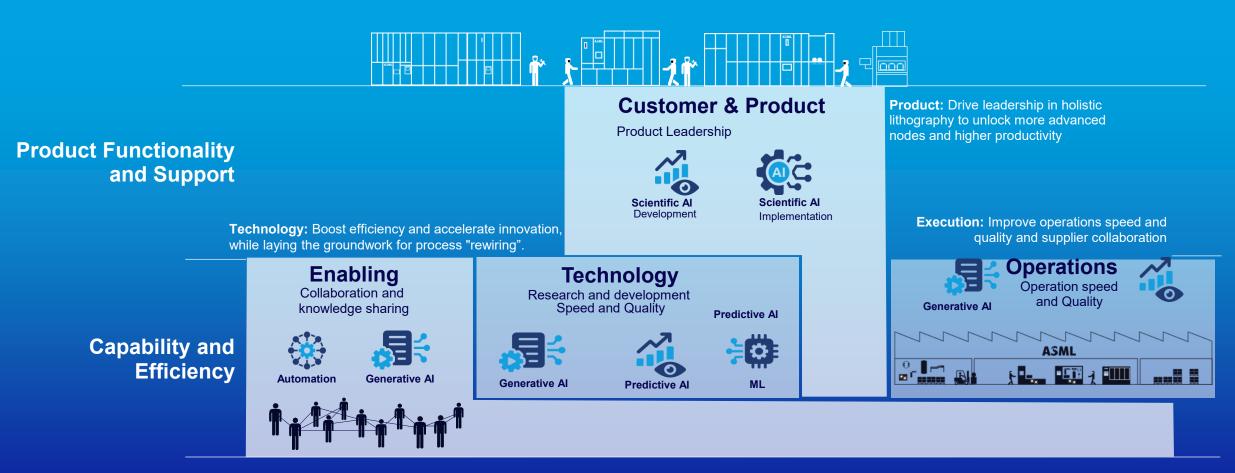
Al potential: from design contribution to customer value

First results available, many more feasibility studies to start across holistic litho triangle



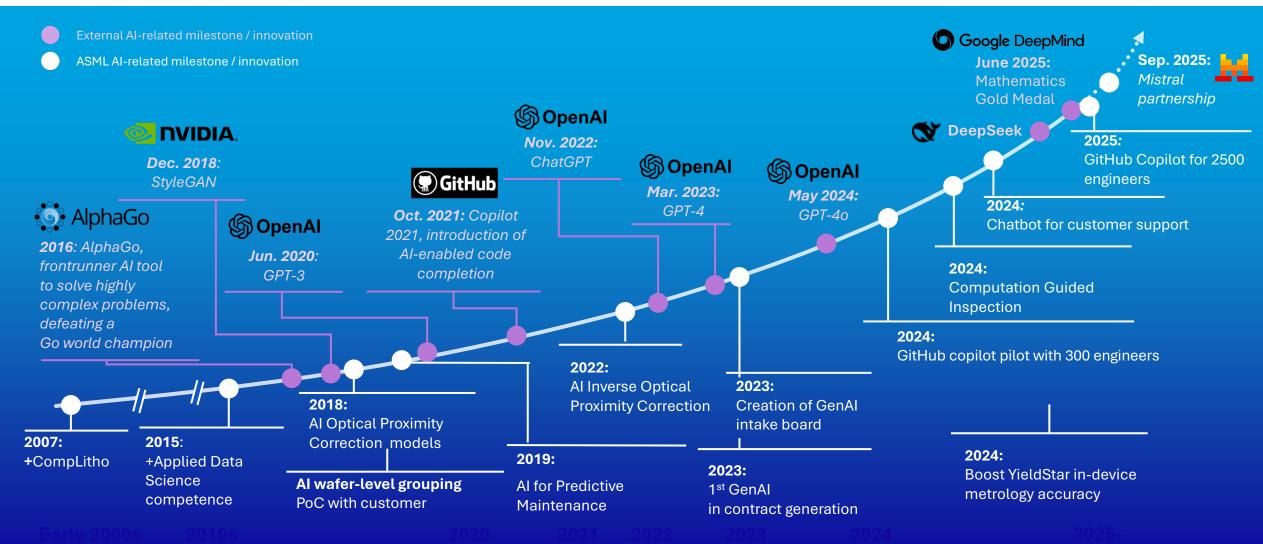
Al is a key to accelerate innovation and tackle complexity in development

Al strategy and roadmap in place for all key domains of ASML



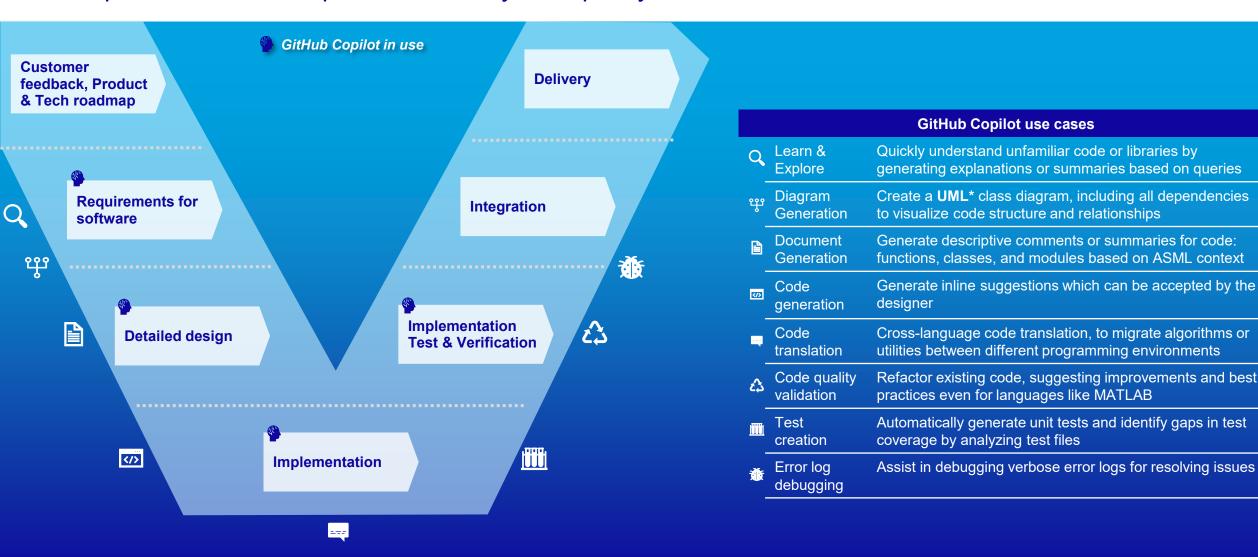
Enabling: Support ASML scaling by accelerating time to market, enhancing quality, driving operational performance and productivity

Al is not new to ASML: Responding to industry trends, we have taken great steps towards Al enablement

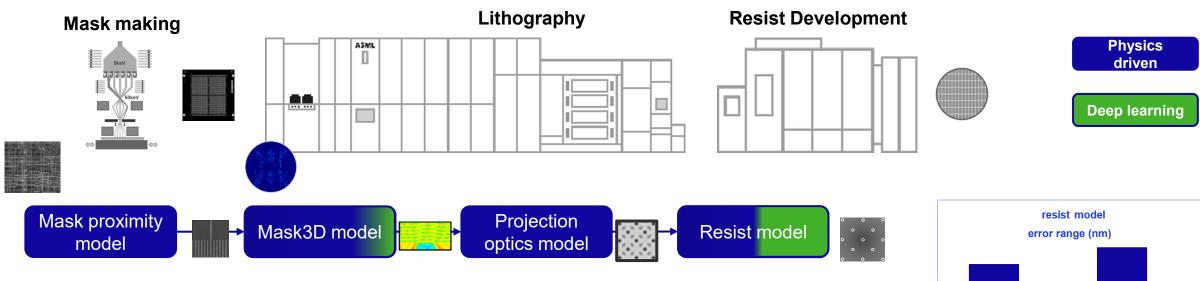


Show case 1: GitHub Copilot integrated in entire Software Value Stream

To improve code development efficiency and quality



Show case 2: Computational lithography model incorporates physics knowledge and deep learning technology to achieve superior accuracy



Empirical model

- Complex physics / chemistry but small effects
- Models key effects with 10⁰-10¹ empirical parameters

Physical + ML model

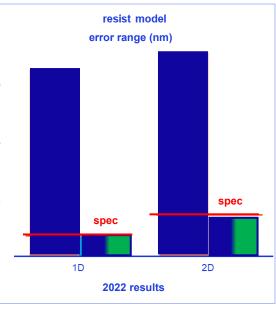
- Maxwell equation solver is too slow (by ~ 10⁶) for fullchip applications
- Simulated data used to train a hybrid model with 10³-10⁴ parameters

Physical model

- Physical model including scanner effects
- All parameters are physical

Physics Informed ML model

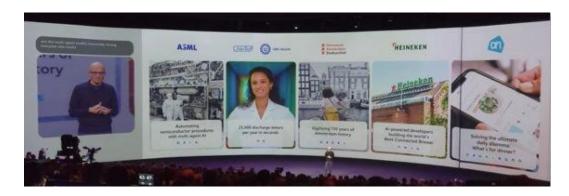
- Complex physics / chemistry difficult to be modeled efficiently
- Wafer data and simulated data (from semi-physical model) combined to train a deep learning model with 10³-10⁴ parameters



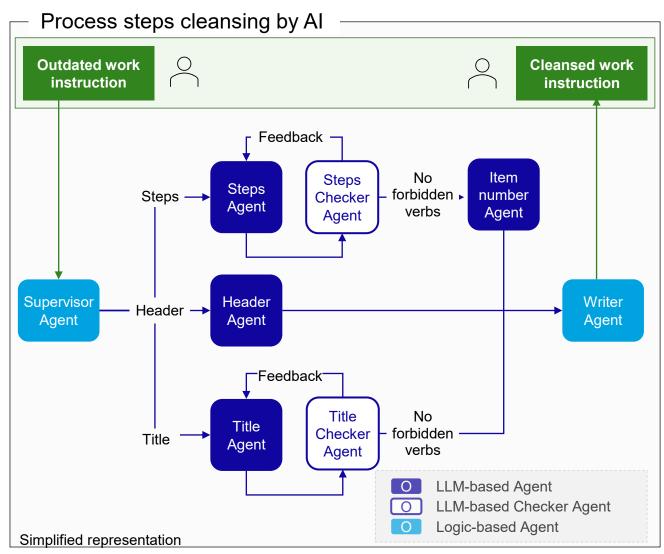
Show case 3: Feasibility study shows that GenAl can reduce manual effort for work instructions update

Business context

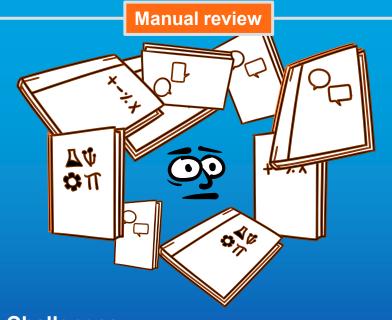
- 90K+ work instructions, used by 15K+ employees to build, install and service systems for their customers
- work instructions updated 2x per year, to ensure compliance with latest standards on content and structure
- GenAl shows better quality, shorter labor duration with human-in-the-loop



Work pitched by MSFT CEO during GenAl conference in Amsterdam in 2025



Show case 4: Improving customer support capability by leveraging ChatBot in software release documents



Challenges:

- Release bulletins require in-depth technical description of new functions and issue resolution for customers
- Lengthy release bulletins need to be generated by iterative manual process and reviews.

Al translates technical description



to customer descriptions for release bulletins, ...



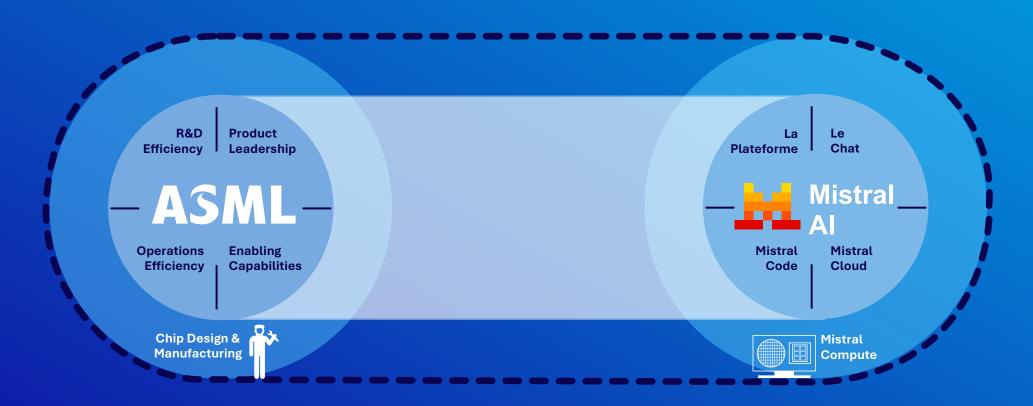
Improvements:

- Experts review and approve AI-generated customer description ("human in the loop"),
- Empowered by ChatBot, it simplifies the tasks to identify specific customer relevant features, improvements, bug fixes, and assess potential risks for upgrade.



ASML does not do this alone

The strategic partnership with Mistral will help us to strengthen our core competence and to support future customer value



ASML

Thank you!